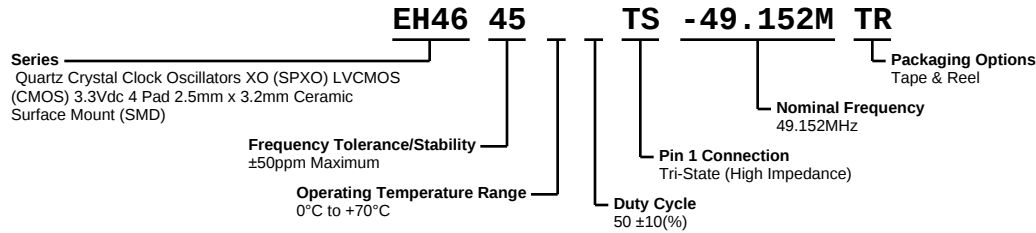


EH4645TS-49.152M TR



ELECTRICAL SPECIFICATIONS

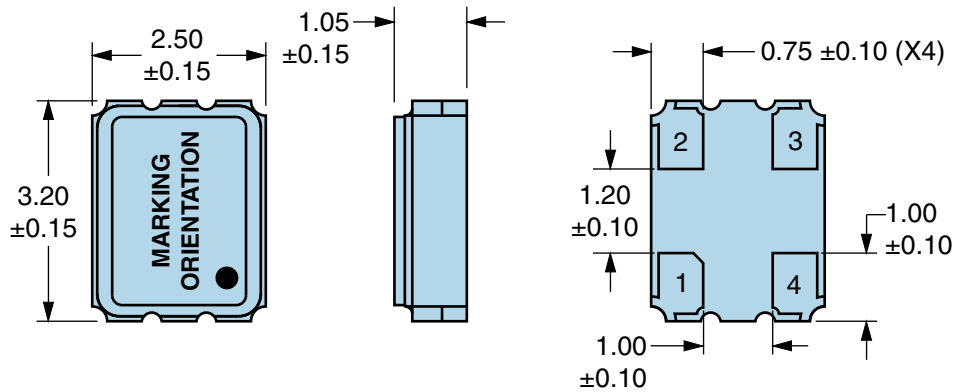
Nominal Frequency	49.152MHz
Frequency Tolerance/Stability	± 50 ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25° , 260°C Reflow, Shock, and Vibration)
Aging at 25°C	± 5 ppm/Year Maximum
Operating Temperature Range	0°C to $+70^{\circ}\text{C}$
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	12mA Maximum (No Load)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -8mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +8mA)
Rise/Fall Time	6nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	$50 \pm 10(\%)$ (Measured at 50% of waveform)
Load Drive Capability	30pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10 μ A Maximum (Pin 1 = Ground)
RMS Phase Jitter	20pSec Typical, 30pSec Maximum (Fj = 12kHz to 20MHz)
Period Jitter (RMS)	10pSec Typical
Period Jitter (pk-pk)	60pSec Typical, 100pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to $+125^{\circ}\text{C}$

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500Vdc
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

EH4645TS-49.152M TR

MECHANICAL DIMENSIONS (all dimensions in millimeters)

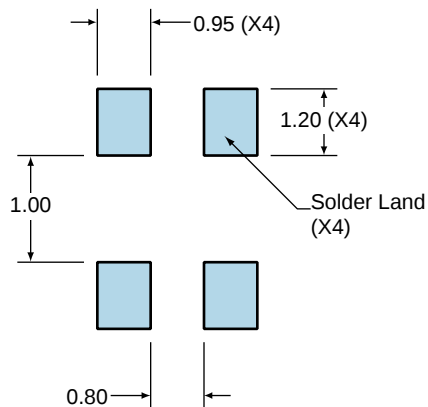


PIN	CONNECTION
1	Tri-State
2	Case Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	E49.152 E=Ecliptek Designator
2	XXXXXX XXXXXX=Ecliptek Manufacturing Identifier

Suggested Solder Pad Layout

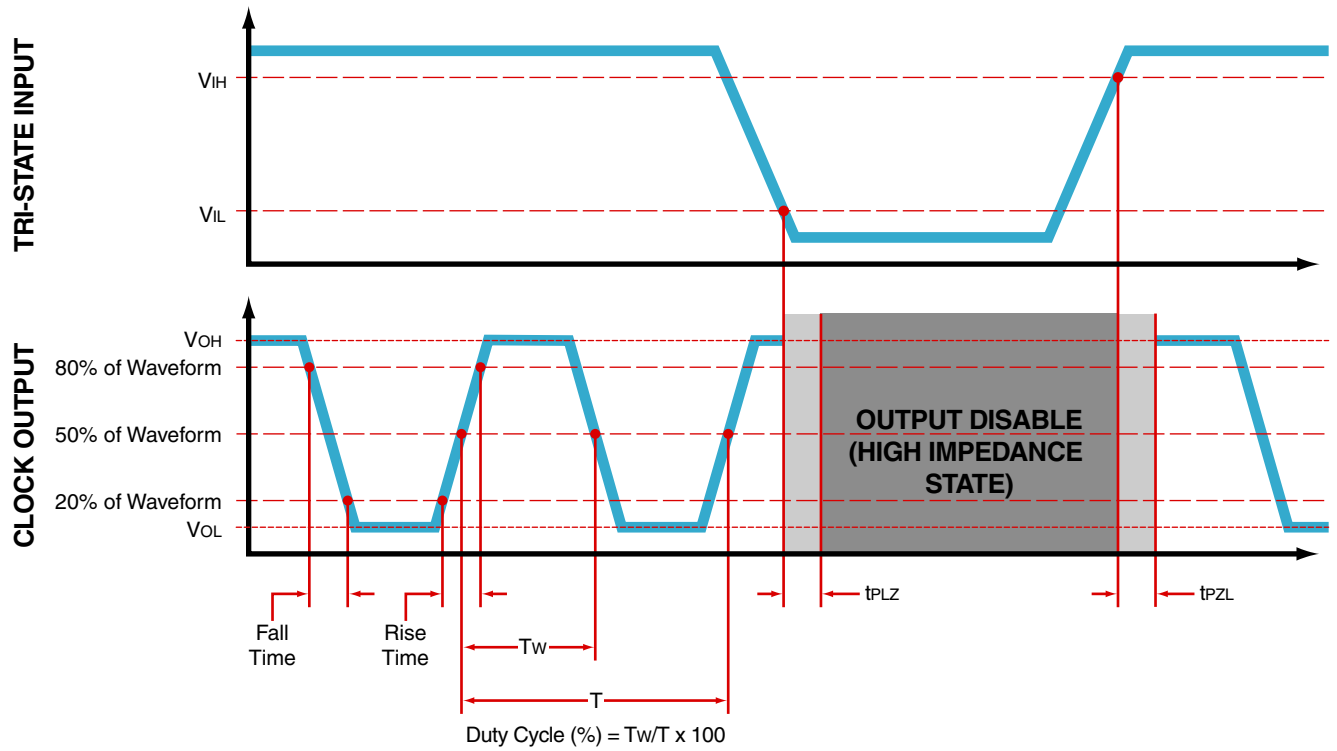
All Dimensions in Millimeters



All Tolerances are ± 0.1

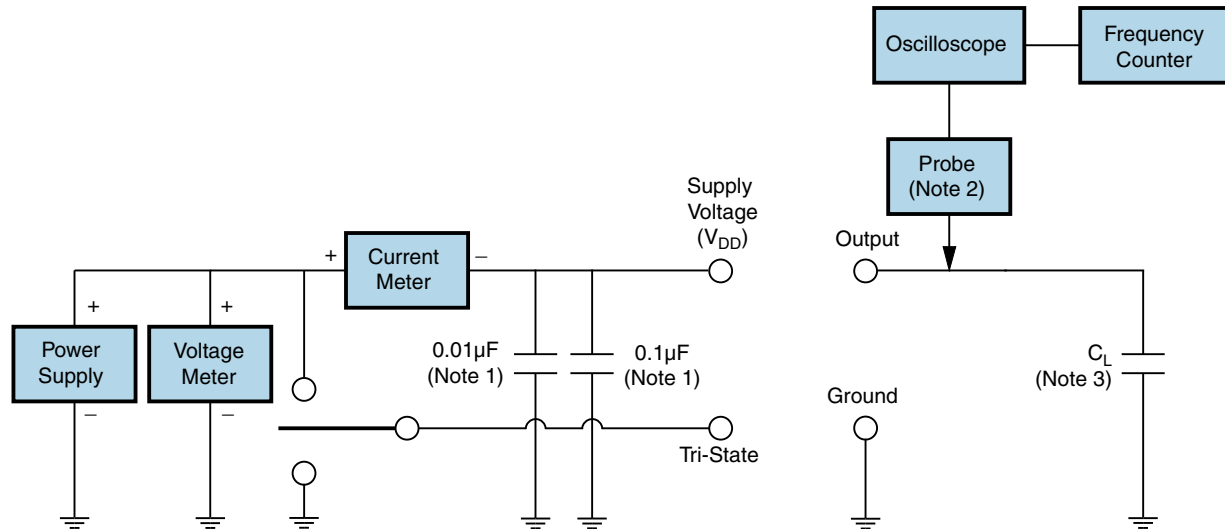
EH4645TS-49.152M TR

OUTPUT WAVEFORM & TIMING DIAGRAM



EH4645TS-49.152M TR

Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

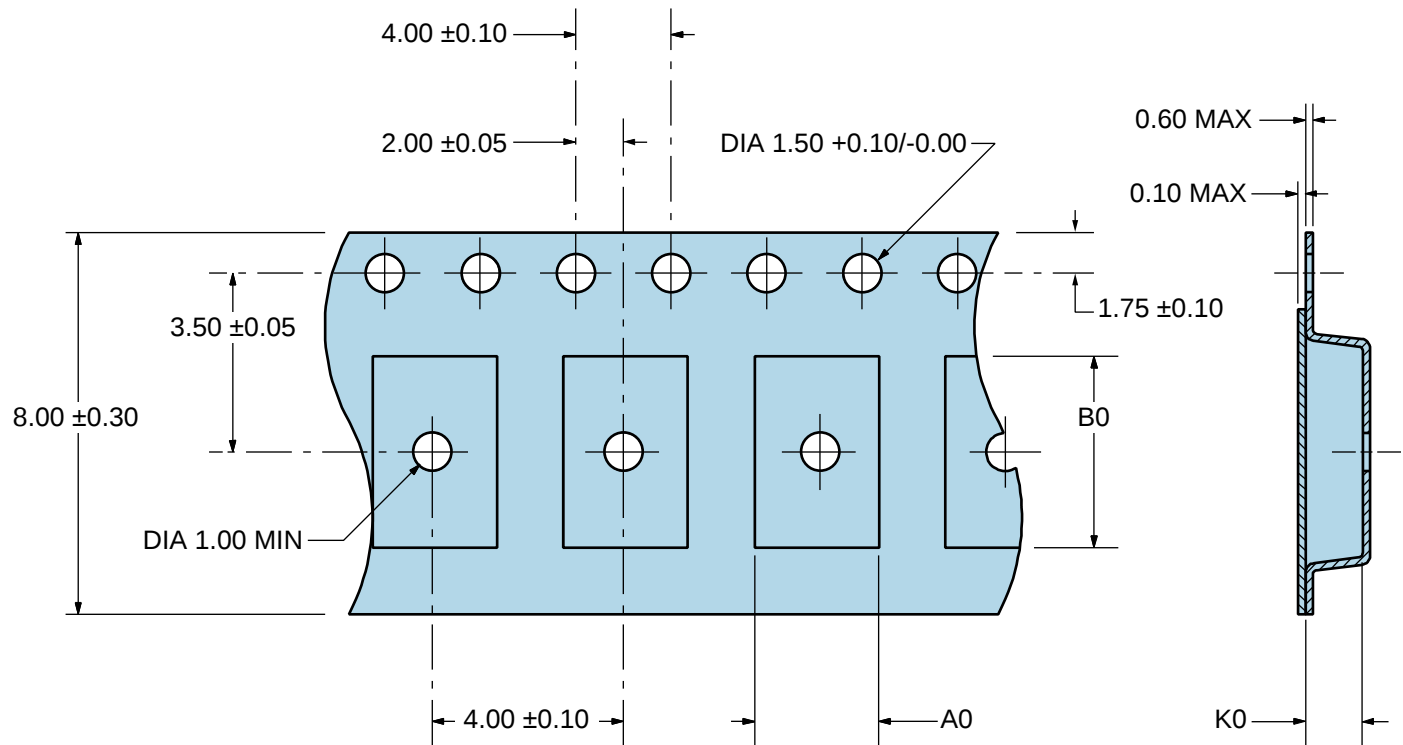
Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

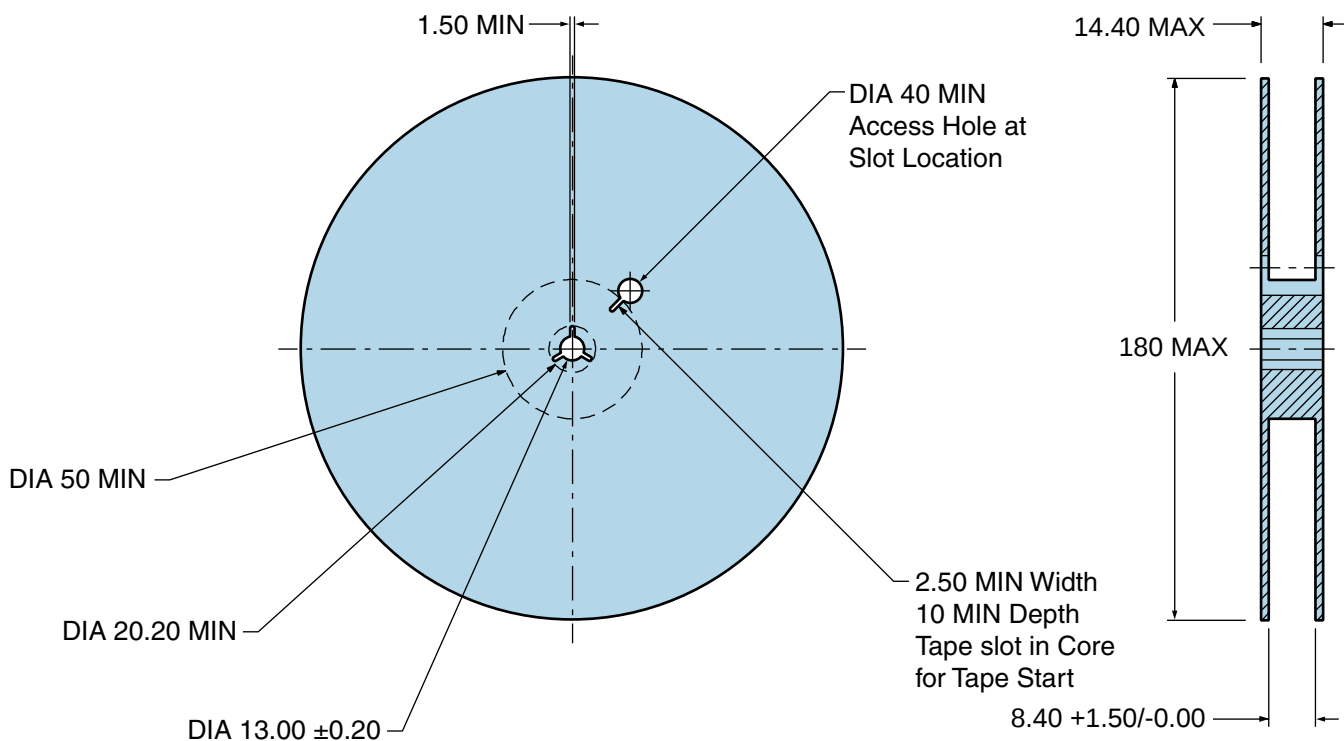
EH4645TS-49.152M TR

Tape & Reel Dimensions

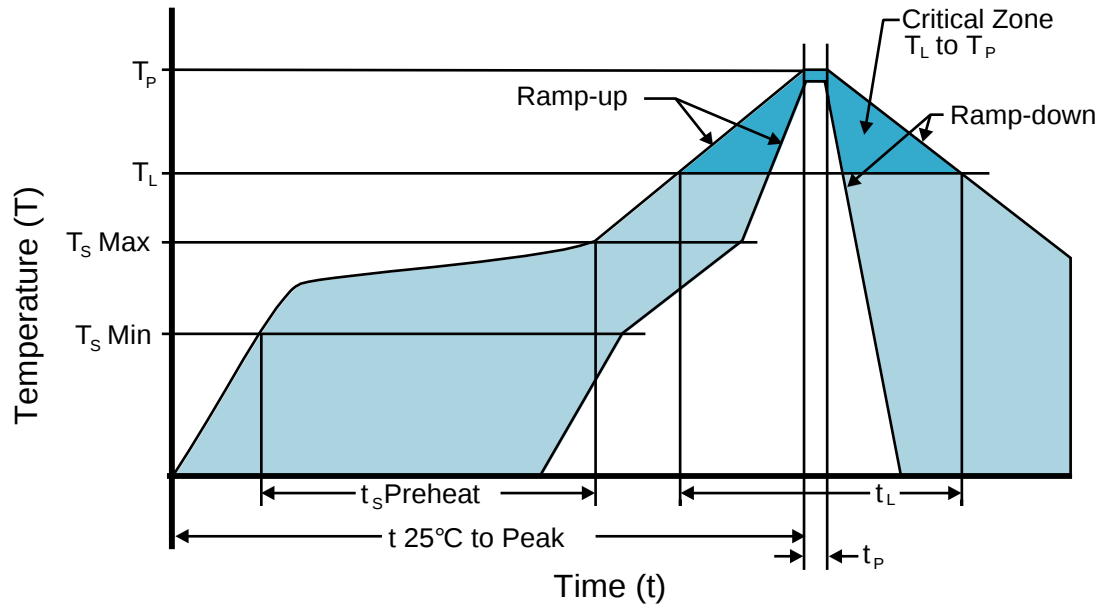
All Dimensions in Millimeters
 Quantity Per Reel: 1,000 units



Note: Compliant to EIA 481



Recommended Solder Reflow Methods



High Temperature Infrared/Convection

$T_s \text{ MAX}$ to T_L (Ramp-up Rate) 3°C/second Maximum

Preheat

- Temperature Minimum ($T_s \text{ MIN}$) 150°C
- Temperature Typical ($T_s \text{ TYP}$) 175°C
- Temperature Maximum ($T_s \text{ MAX}$) 200°C
- Time ($t_s \text{ MIN}$) 60 - 180 Seconds

Ramp-up Rate (T_L to T_p) 3°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 217°C
- Time (t_L) 60 - 150 Seconds

Peak Temperature (T_p) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature ($T_p \text{ Target}$) 250°C +0/-5°C

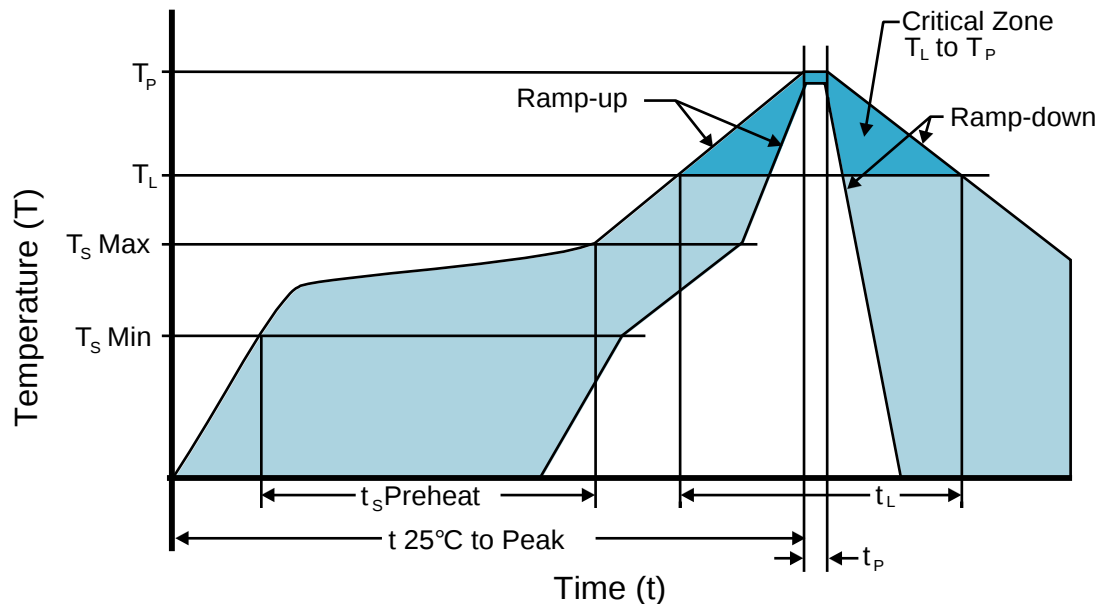
Time within 5°C of actual peak (t_p) 20 - 40 seconds

Ramp-down Rate 6°C/second Maximum

Time 25°C to Peak Temperature (t) 8 minutes Maximum

Moisture Sensitivity Level Level 1

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

Ts MAX to Tl (Ramp-up Rate) 5°C/second Maximum

Preheat

- Temperature Minimum (Ts MIN) N/A
- Temperature Typical (Ts TYP) 150°C
- Temperature Maximum (Ts MAX) N/A
- Time (ts MIN) 60 - 120 Seconds

Ramp-up Rate (Tl to Tp) 5°C/second Maximum

Time Maintained Above:

- Temperature (Tl) 150°C
- Time (tL) 200 Seconds Maximum

Peak Temperature (Tp) 240°C Maximum

Target Peak Temperature (Tp Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (tp) 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.